

Title (en)

INDUCTIVE COMPONENTS AND METHODS OF FORMING INDUCTIVE COMPONENTS

Title (de)

INDUKTIVE KOMPONENTE UND VERFAHREN ZUR FORMUNG VON INDUKTIVEN KOMPONENTEN

Title (fr)

COMPOSANTS INDUCTIFS ET PROCÉDÉS DE FORMATION DE COMPOSANTS INDUCTIFS

Publication

EP 3719819 A1 20201007 (EN)

Application

EP 19166782 A 20190402

Priority

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Abstract (en)

An inductive component comprising: a substrate comprising a plurality of layers; magnetic material; and at least one coil of conductive thread wound through the substrate to mechanically interconnect the plurality of layers, wherein at least a portion of the at least one coil of conductive thread is located around at least a portion of the magnetic material.

IPC 8 full level

H01F 17/00 (2006.01); **H01F 41/06** (2016.01)

CPC (source: EP)

H01F 17/0013 (2013.01); **H01F 41/06** (2013.01); **H01F 2017/0066** (2013.01)

Citation (search report)

- [X] US 2007230049 A1 20071004 - FUJIWARA TOSHIYASU [JP], et al
- [X] JP 2009231134 A 20091008 - TOSHIBA LIGHTING & TECHNOLOGY
- [X] JP 2007273803 A 20071018 - TDK CORP
- [X] JP 2007273802 A 20071018 - TDK CORP
- [X] JP H05109557 A 19930430 - NIPPON TELEGRAPH & TELEPHONE
- [X] US 2012194314 A1 20120802 - MO CHIA-PING [TW]
- [A] US 2015048918 A1 20150219 - PARK JEONG WOO [KR], et al
- [A] US 2018033533 A1 20180201 - RYU HAN WOOL [KR], et al

Cited by

CN114461060A; GB2602380A; GB2602380B; US11716006B2

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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